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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	8051
Core Size	8-Bit
Speed	18MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	26
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	28-TSSOP
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/p89lpc980fdh-529

7. Functional description

Remark: Please refer to the P89LPC980/982/983/985 *User manual* for a more detailed functional description.

7.1 Special function registers

Remark: SFR accesses are restricted in the following ways:

- User must **not** attempt to access any SFR locations not defined.
- Accesses to any defined SFR locations must be strictly for the functions for the SFRs.
- SFR bits labeled '-', '0' or '1' can **only** be written and read as follows:
  - '-' Unless otherwise specified, **must** be written with '0', but can return any value when read (even if it was written with '0'). It is a reserved bit and may be used in future derivatives.
  - '0' **must** be written with '0', and will return a '0' when read.
  - '1' **must** be written with '1', and will return a '1' when read.

Table 4. Special function registers - P89LPC980/982

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
	Bit address		E7	E6	E5	E4	E3	E2	E1	E0		
ACC*	Accumulator	E0H									00	0000 0000
AUXR1	Auxiliary function register	A2H	CLKLP	EBRR	ENT1	ENT0	SRST	0	-	DPS	00	0000 00x0
	Bit address		F7	F6	F5	F4	F3	F2	F1	F0		
B*	B register	F0H									00	0000 0000
BRGR0[1]	Baud rate generator 0 rate low	BEH									00	0000 0000
BRGR1[1]	Baud rate generator 0 rate high	BFH									00	0000 0000
BRGCON	Baud rate generator 0 control	BDH	-	-	-	-	-	-	SBRGS	BRGEN	00[1]	xxxx xx00
CMP1	Comparator 1 control register	ACH	-	-	CE1	CP1	CN1	OE1	CO1	CMF1	00[2]	xx00 0000
CMP2	Comparator 2 control register	ADH	-	-	CE2	CP2	CN2	OE2	CO2	CMF2	00[2]	xx00 0000
DIVM	CPU clock divide-by-M control	95H									00	0000 0000
DPTR	Data pointer (2 bytes)											
DPH	Data pointer high	83H									00	0000 0000
DPL	Data pointer low	82H									00	0000 0000
FMADRH	Program flash address high	E7H									00	0000 0000
FMADRL	Program flash address low	E6H									00	0000 0000

Table 4. Special function registers - P89LPC980/982 *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
PWMD4L	PWM Free Cycle Register 4 Low Byte	ABH									00	0000 0000
RCAP2H	Capture Register 2 High Byte	FCH									00	0000 0000
RCAP2L	Capture Register 2 Low Byte	FBH									00	0000 0000
RCAP3H	Capture Register 3 High Byte	ECH									00	0000 0000
RCAP3L	Capture Register 3 Low Byte	EBH									00	0000 0000
RCAP4H	Capture Register 4 High Byte	CAH									00	0000 0000
RCAP4L	Capture Register 4 Low Byte	C9H									00	0000 0000
RSTSRC	Reset source register	DFH	-	BOIF	BORF	POF	R_KB	R_WD	R_SF	R_EX	[3]	
RTCCON	RTC control	D1H	RTCF	RTCS1	RTCS0	-	-	-	ERTC	RTCEN	60[2][4]	011x xx00
RTCH	RTC register high	D2H									00[4]	0000 0000
RTCL	RTC register low	D3H									00[4]	0000 0000
SADDR	Serial port address register	A9H									00	0000 0000
SADEN	Serial port address enable	B9H									00	0000 0000
SBUF	Serial Port data buffer register	99H									xx	xxxx xxxx
	Bit address		**9F**	**9E**	**9D**	**9C**	**9B**	**9A**	**99**	**98**		
SCON*	Serial port control	98H	SM0/FE	SM1	SM2	REN	TB8	RB8	TI	RI	00	0000 0000
SSTAT	Serial port extended status register	BAH	DBMOD	INTLO	CIDIS	DBISEL	FE	BR	OE	STINT	00	0000 0000
SP	Stack pointer	81H									07	0000 0111

Table 4. Special function registers - P89LPC980/982 *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
SPCTL	SPI control register	E2H	SSIG	SPEN	DORD	MSTR	CPOL	CPHA	SPR1	SPR0	04	0000 0100
SPSTAT	SPI status register	E1H	SPIF	WCOL	-	-	-	-	-	-	00	00xx xxxx
SPDAT	SPI data register	E3H									00	0000 0000
TAMOD	Timer 0 and 1 auxiliary mode	8FH	-	-	-	T1M2	-	-	-	T0M2	00	xxx0 xxx0
	Bit address		**8F**	**8E**	**8D**	**8C**	**8B**	**8A**	**89**	**88**		
TCON*	Timer 0 and 1 control	88H	TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0	00	0000 0000
TH0	Timer 0 high	8CH									00	0000 0000
TH1	Timer 1 high	8DH									00	0000 0000
TL0	Timer 0 low	8AH									00	0000 0000
TL1	Timer 1 low	8BH									00	0000 0000
TMOD	Timer 0 and 1 mode	89H	T1GATE	T1C/T	T1M1	T1M0	T0GATE	T0C/T	T0M1	T0M0	00	0000 0000
T2CON	Timer/Counter 2 Control	FFH	PSEL2	ENT2	TIEN2	PWM2	EXEN2	TR2	C/NT2	CP/NRL2	00	0000 0000
TH2	Timer/Counter 2 High Byte	FEH									00	0000 0000
TL2	Timer/Counter 2 Low Byte	FDH									00	0000 0000
T3CON	Timer/Counter 3 Control	EFH	PSEL3	ENT3	TIEN3	PWM3	EXEN3	TR3	C/NT3	CP/NRL3	00	0000 0000
TH3	Timer/Counter 3 High Byte	EEH									00	0000 0000
TL3	Timer/Counter 3 Low Byte	EDH									00	0000 0000
T4CON	Timer/Counter 2 Control	CDH	PSEL4	ENT4	TIEN4	PWM4	EXEN4	TR4	C/NT4	CP/NRL4	00	0000 0000
TH4	Timer/Counter 4 High Byte	CCH									00	0000 0000

Table 6. Special function registers - P89LPC983/985 *…continued*

** indicates SFRs that are bit addressable.*

Name	Description	SFR addr.	Bit functions and addresses								Reset value	
			MSB							LSB	Hex	Binary
TH3	Timer/Counter 3 High Byte	EEH									00	0000 0000
TL3	Timer/Counter 3 Low Byte	EDH									00	0000 0000
T4CON	Timer/Counter 2 Control	CDH	PSEL4	ENT4	TIEN4	PWM4	EXEN4	TR4	C/NT4	CP/NRL4	00	0000 0000
TH4	Timer/Counter 4 High Byte	CCH									00	0000 0000
TL4	Timer/Counter 4 Low Byte	CBH									00	0000 0000
TINTF	Timer/Counters 2/3/4 Overflow and External Flags	CEH	-	-	TF4	EXF4	TF3	EXF3	TF2	EXF2	00	0000 0000
TRIM	Internal oscillator trim register	96H	RCCLK	ENCLK	TRIM.5	TRIM.4	TRIM.3	TRIM.2	TRIM.1	TRIM.0	[4][5]	
WDCON	Watchdog control register	A7H	PRE2	PRE1	PRE0	-	-	WDRUN	WDTOF	WDCLK	[4][6]	
WDL	Watchdog load	C1H									FF	1111 1111
WFEED1	Watchdog feed 1	C2H										
WFEED2	Watchdog feed 2	C3H										

[1] BRGR1 and BRGR0 must only be written if BRGEN in BRGCON SFR is logic 0. If any are written while BRGEN = 1, the result is unpredictable.

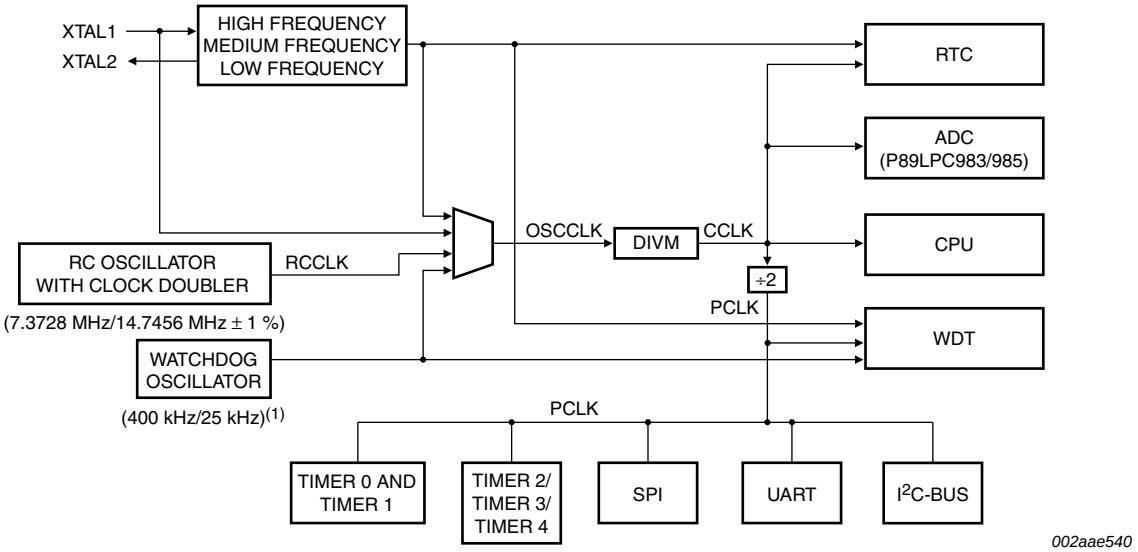
[2] All ports are in input only (high-impedance) state after power-up.

[3] The RSTSRC register reflects the cause of the P89LPC980/982/983/985 reset except BOIF bit. Upon a power-up reset, all reset source flags are cleared except POF and BOF; the power-on reset value is x011 0000.

[4] The only reset sources that affect these SFRs are power-on reset and watchdog reset.

[5] On power-on reset and watchdog reset, the TRIM SFR is initialized with a factory preprogrammed value. Other resets will not cause initialization of the TRIM register.

[6] After reset, the value is 1110 01x1, i.e., PRE2 to PRE0 are all logic 1, WDRUN = 1 and WDCLK = 1. WDTOF bit is logic 1 after watchdog reset and is logic 0 after power-on reset. Other resets will not affect WDTOF.



(1) ±10 % at 400 kHz.

Fig 9. Block diagram of oscillator control

7.10 CCLK wake-up delay

The P89LPC980/982/983/985 has an internal wake-up timer that delays the clock until it stabilizes depending on the clock source used. If the clock source is any of the three crystal selections (low, medium and high frequencies) the delay is 1024 OSCCLK cycles plus 60 μs to 100 μs. If the clock source is the internal RC oscillator, the delay is 200 μs to 300 μs. If the clock source is watchdog oscillator or external clock, the delay is 32 OSCCLK cycles.

7.11 CCLK modification: DIVM register

The OSCCLK frequency can be divided down up to 510 times by configuring a dividing register, DIVM, to generate CCLK. This feature makes it possible to temporarily run the CPU at a lower rate, reducing power consumption. By dividing the clock, the CPU can retain the ability to respond to events that would not exit Idle mode by executing its normal program at a lower rate. This can also allow bypassing the oscillator start-up time in cases where Power-down mode would otherwise be used. The value of DIVM may be changed by the program at any time without interrupting code execution.

7.12 Low power select

The P89LPC980/982/983/985 is designed to run at 18 MHz (CCLK) maximum. However, if CCLK is 8 MHz or slower, the CLKLP SFR bit (AUXR1.7) can be set to logic 1 to lower the power consumption further. On any reset, CLKLP is logic 0 allowing highest performance access. This bit can then be set in software if CCLK is running at 8 MHz or slower.

7.16 I/O ports

The P89LPC980/982/983/985 has four I/O ports: Port 0, Port 1, Port 2 and Port 3. Ports 0, 1, and 2 are 8-bit ports, and Port 3 is a 2-bit port. The exact number of I/O pins available depends upon the clock and reset options chosen, as shown in Table 9.

Table 9. Number of I/O pins available

Clock source	Reset option	Number of I/O pins (28-pin package)
On-chip oscillator or watchdog oscillator	No external reset (except during power-up)	26
	External $\overline{\text{RST}}$ pin supported	25
External clock input	No external reset (except during power-up)	25
	External $\overline{\text{RST}}$ pin supported	24
Low/medium/high speed oscillator (external crystal or resonator)	No external reset (except during power-up)	24
	External $\overline{\text{RST}}$ pin supported	23

7.16.1 Port configurations

All but three I/O port pins on the P89LPC980/982/983/985 may be configured by software to one of four types on a bit-by-bit basis. These are: quasi-bidirectional (standard 80C51 port outputs), push-pull, open drain, and input-only. Two configuration registers for each port select the output type for each port pin.

1. P1.5 ($\overline{\text{RST}}$) can only be an input and cannot be configured.
2. P1.2 (SCL/T0) and P1.3 (SDA/$\overline{\text{INT0}}$) may only be configured to be either input-only or open-drain.

7.16.1.1 Quasi-bidirectional output configuration

Quasi-bidirectional output type can be used as both an input and output without the need to reconfigure the port. This is possible because when the port outputs a logic HIGH, it is weakly driven, allowing an external device to pull the pin LOW. When the pin is driven LOW, it is driven strongly and able to sink a fairly large current. These features are somewhat similar to an open-drain output except that there are three pull-up transistors in the quasi-bidirectional output that serve different purposes.

A quasi-bidirectional port pin has a Schmitt trigger input that also has a glitch suppression circuit.

7.16.1.2 Open-drain output configuration

The open-drain output configuration turns off all pull-ups and only drives the pull-down transistor of the port driver when the port latch contains a logic 0. To be used as a logic output, a port configured in this manner must have an external pull-up, typically a resistor tied to V_{DD}.

An open-drain port pin has a Schmitt trigger input that also has a glitch suppression circuit.

7.19 Timers/counters 0 and 1

The P89LPC980/982/983/985 has two general purpose counter/timers which are upward compatible with the standard 80C51 Timer 0 and Timer 1. Both can be configured to operate either as timers or event counters. An option to automatically toggle the T0 or T1 pins upon timer overflow has been added.

In the 'Timer' function, the register is incremented every machine cycle.

In the 'Counter' function, the register is incremented in response to a 1-to-0 transition at its corresponding count input pin, T0 or T1. In this function, the count input is sampled once during every machine cycle.

Timer 0 and Timer 1 have five operating modes (Modes 0, 1, 2, 3 and 6). Modes 0, 1, 2 and 6 are the same for both Timers/Counters. Mode 3 is different.

7.19.1 Mode 0

Putting either Timer into Mode 0 makes it look like an 8048 Timer, which is an 8-bit Counter with a divide-by-32 prescaler. In this mode, the Timer register is configured as a 13-bit register. Mode 0 operation is the same for Timer 0 and Timer 1.

7.19.2 Mode 1

Mode 1 is the same as Mode 0, except that all 16 bits of the timer register are used.

7.19.3 Mode 2

Mode 2 configures the Timer register as an 8-bit Counter with automatic reload. Mode 2 operation is the same for Timer 0 and Timer 1.

7.19.3.1 Mode 3

When Timer 1 is in Mode 3 it is stopped. Timer 0 in Mode 3 forms two separate 8-bit counters and is provided for applications that require an extra 8-bit timer. When Timer 1 is in Mode 3 it can still be used by the serial port as a baud rate generator.

7.19.3.2 Mode 6

In this mode, the corresponding timer can be changed to a PWM with a full period of 256 timer clocks.

7.19.4 Timer overflow toggle output

Timers 0 and 1 can be configured to automatically toggle a port output whenever a timer overflow occurs. The same device pins that are used for the T0 and T1 count inputs are also used for the timer toggle outputs. The port outputs will be a logic 1 prior to the first timer overflow when this mode is turned on.

7.20 Timers/counters 2, 3 and 4

The P89LPC980/982/983/985 has three external 16-bit timer/counters. All can be configured to operate either as timers or event counters. An option to automatically toggle pin Tx (x = 2, 3 or 4) upon timer overflow has been added.

In the 'Timer' function, the register is incremented every PCLK.

automatic address recognition, selectable double buffering and several interrupt options. The UART can be operated in four modes: shift register, 8-bit UART, 9-bit UART, and CPU clock/32 or CPU clock/16.

7.22.1 Mode 0

Serial data enters and exits through RXD. TXD outputs the shift clock. 8 bits are transmitted or received, LSB first. The baud rate is fixed at $1/16$ of the CPU clock frequency.

7.22.2 Mode 1

10 bits are transmitted (through TXD) or received (through RXD): a start bit (logic 0), 8 data bits (LSB first), and a stop bit (logic 1). When data is received, the stop bit is stored in RB8 in special function register SCON. The baud rate is variable and is determined by the Timer 1 overflow rate or the baud rate generator (described in Section 7.22.5 “Baud rate generator and selection”).

7.22.3 Mode 2

11 bits are transmitted (through TXD) or received (through RXD): start bit (logic 0), 8 data bits (LSB first), a programmable 9th data bit, and a stop bit (logic 1). When data is transmitted, the 9th data bit (TB8 in SCON) can be assigned the value of logic 0 or logic 1. Or, for example, the parity bit (P, in the PSW) could be moved into TB8. When data is received, the 9th data bit goes into RB8 in special function register SCON, while the stop bit is not saved. The baud rate is programmable to either $1/16$ or $1/32$ of the CPU clock frequency, as determined by the SMOD1 bit in PCON.

7.22.4 Mode 3

11 bits are transmitted (through TXD) or received (through RXD): a start bit (logic 0), 8 data bits (LSB first), a programmable 9th data bit, and a stop bit (logic 1). In fact, Mode 3 is the same as Mode 2 in all respects except baud rate. The baud rate in Mode 3 is variable and is determined by the Timer 1 overflow rate or the baud rate generator (described in Section 7.22.5 “Baud rate generator and selection”).

7.22.5 Baud rate generator and selection

The P89LPC980/982/983/985 enhanced UART has an independent baud rate generator. The baud rate is determined by a baud-rate preprogrammed into the BRGR1 and BRGR0 SFRs which together form a 16-bit baud rate divisor value that works in a similar manner as Timer 1 but is much more accurate. If the baud rate generator is used, Timer 1 can be used for other timing functions.

The UART can use either Timer 1 or the baud rate generator output (see Figure 11). Note that Timer T1 is further divided by 2 if the SMOD1 bit (PCON.7) is cleared. The independent baud rate generators use OSCCLK.

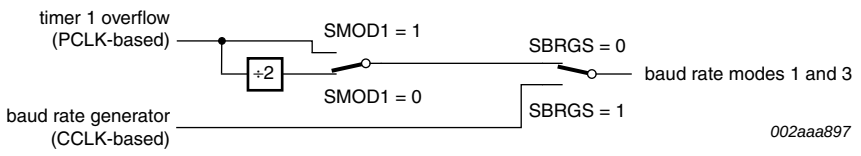


Fig 11. Baud rate sources for UART (Modes 1, 3)

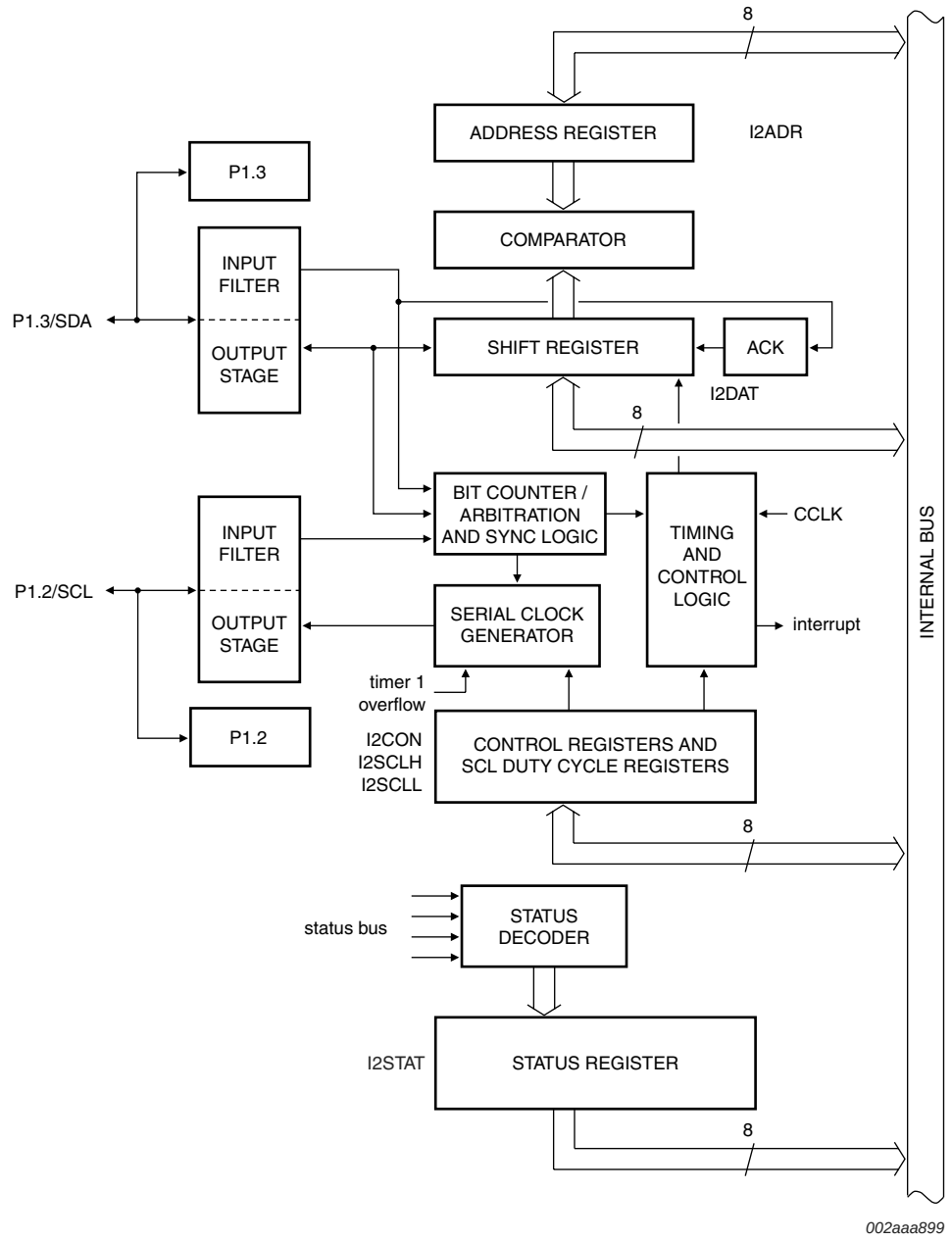
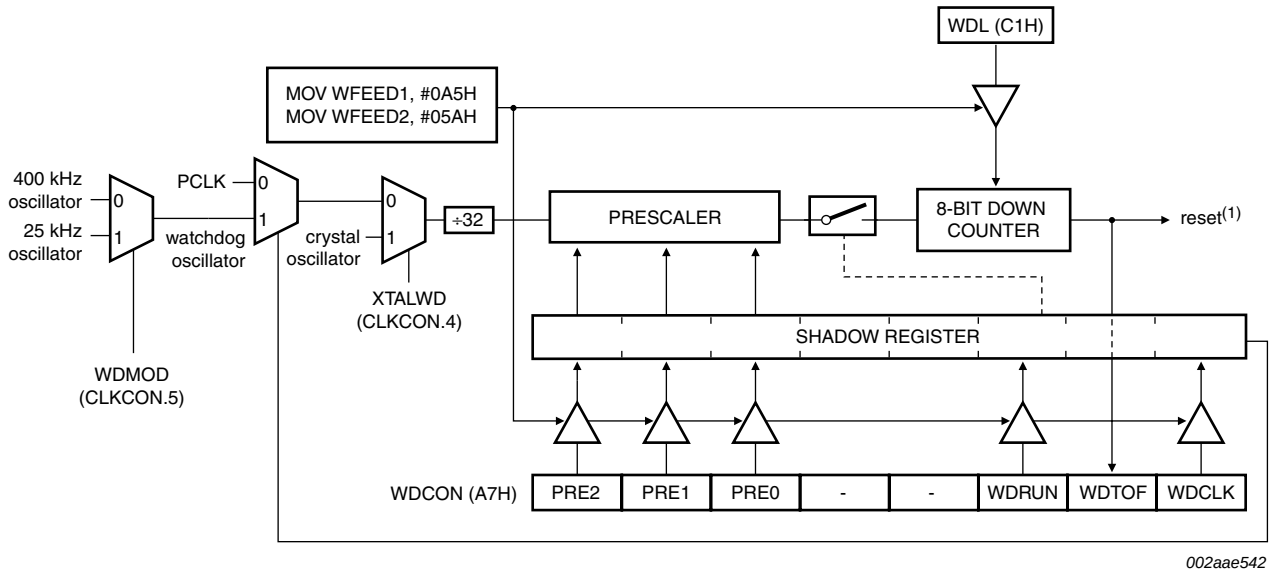


Fig 13. I²C-bus serial interface block diagram



(1) Watchdog reset can also be caused by an invalid feed sequence, or by writing to WDCON not immediately followed by a feed sequence.

Fig 19. Watchdog timer in Watchdog mode (WDTE = 1)

7.28 Additional features

7.28.1 Software reset

The SRST bit in AUXR1 gives software the opportunity to reset the processor completely, as if an external reset or watchdog reset had occurred. Care should be taken when writing to AUXR1 to avoid accidental software resets.

7.28.2 Dual data pointers

The dual Data Pointers (DPTR) provides two different Data Pointers to specify the address used with certain instructions. The DPS bit in the AUXR1 register selects one of the two Data Pointers. Bit 2 of AUXR1 is permanently wired as a logic 0 so that the DPS bit may be toggled (thereby switching Data Pointers) simply by incrementing the AUXR1 register, without the possibility of inadvertently altering other bits in the register.

7.29 Flash program memory

7.29.1 General description

The P89LPC980/982/983/985 flash memory provides in-circuit electrical erasure and programming. The flash can be erased, read, and written as bytes. The Sector and Page Erase functions can erase any flash sector (1 kB) or page (64 bytes). The Chip Erase operation will erase the entire program memory. ICP using standard commercial programmers is available. In addition, IAP and byte-erase allows code memory to be used for non-volatile data storage. On-chip erase and write timing generation contribute to a user-friendly programming interface. The P89LPC980/982/983/985 flash reliably stores memory contents even after 100000 erase and program cycles. The cell is designed to

7.29.6 ICP

ICP is performed without removing the microcontroller from the system. The ICP facility consists of internal hardware resources to facilitate remote programming of the P89LPC980/982/983/985 through a two-wire serial interface. The NXP ICP facility has made in-circuit programming in an embedded application - using commercially available programmers - possible with a minimum of additional expense in components and circuit board area. The ICP function uses five pins. Only a small connector needs to be available to interface your application to a commercial programmer in order to use this feature. Additional details may be found in the *P89LPC980/982/983/985 User manual*.

7.29.7 IAP

IAP is performed in the application under the control of the microcontroller's firmware. The IAP facility consists of internal hardware resources to facilitate programming and erasing. The NXP IAP has made in-application programming in an embedded application possible without additional components. Two methods are available to accomplish IAP. A set of predefined IAP functions are provided in a Boot ROM and can be called through a common interface, PGM_MTP. Several IAP calls are available for use by an application program to permit selective erasing and programming of flash sectors, pages, security bits, configuration bytes, and device ID. These functions are selected by setting up the microcontroller's registers before making a call to PGM_MTP at FF03H. The Boot ROM occupies the program memory space at the top of the address space from FF00H to FEFFH, thereby not conflicting with the user program memory space.

In addition, IAP operations can be accomplished through the use of four SFRs consisting of a control/status register, a data register, and two address registers. Additional details may be found in the *P89LPC980/982/983/985 User manual*.

7.29.8 ISP

ISP is performed without removing the microcontroller from the system. The ISP facility consists of a series of internal hardware resources coupled with internal firmware to facilitate remote programming of the P89LPC980/982/983/985 through the serial port. This firmware is provided by NXP and embedded within each P89LPC980/982/983/985 device. The NXP ISP facility has made in-system programming in an embedded application possible with a minimum of additional expense in components and circuit board area. The ISP function uses five pins (V_{DD}, V_{SS}, TXD, RXD, and $\overline{RST}$). Only a small connector needs to be available to interface your application to an external circuit in order to use this feature.

7.29.9 Power-on reset code execution

The P89LPC980/982/983/985 contains two special flash elements: the Boot Vector and the Boot Status bit. Following reset, the P89LPC980/982/983/985 examines the contents of the Boot Status bit. If the Boot Status bit is set to zero, power-up execution starts at location 0000H, which is the normal start address of the user's application code. When the Boot Status bit is set to a value other than zero, the contents of the Boot Vector are used as the high byte of the execution address and the low byte is set to 00H.

Table 11 shows the factory default Boot Vector setting for these devices. A factory-provided bootloader is pre-programmed into the address space indicated and uses the indicated bootloader entry point to perform ISP functions. This code can be erased by the user.

Remark: Users who wish to use this loader should take precautions to avoid erasing the 1 kB sector that contains this bootloader. Instead, the page erase function can be used to erase the first eight 64-byte pages located in this sector.

A custom bootloader can be written with the Boot Vector set to the custom bootloader, if desired.

Table 11. Default boot vector values and ISP entry points

Device	Default boot vector	Default bootloader entry point	Default bootloader code range	1 kB sector range
P89LPC980	0FH	0F00H	0E00H to 0FFFH	0C00H to 0FFFH
P89LPC982	1FH	1F00H	1E00H to 1FFFH	1C00H to 1FFFH
P89LPC983	0FH	0F00H	0E00H to 0FFFH	0C00H to 0FFFH
P89LPC985	1FH	1F00H	1E00H to 1FFFH	1C00H to 1FFFH

7.29.10 Hardware activation of the bootloader

The bootloader can also be executed by forcing the device into ISP mode during a power-on sequence (see the *P89LPC980/982/983/985 User manual* for specific information). This has the same effect as having a non-zero status byte. This allows an application to be built that will normally execute user code but can be manually forced into ISP operation. If the factory default setting for the boot is changed, it will no longer point to the factory pre-programmed ISP bootloader code. After programming the flash, the status byte should be programmed to zero in order to allow execution of the user's application code beginning at address 0000H.

7.30 User configuration bytes

Some user-configurable features of the P89LPC980/982/983/985 must be defined at power-up and therefore cannot be set by the program after start of execution. These features are configured through the use of the flash byte UCFG1 and UCFG2. Please see the *P89LPC980/982/983/985 User Manual* for additional details.

7.31 User sector security bytes

There are four/eight User Sector Security Bytes on the P89LPC980/982/983/985. Each byte corresponds to one sector. Please see the *P89LPC980/982/983/985 User manual* for additional details.

8. ADC (P89LPC983/985)

8.1 General description

The P89LPC985 has a 10-bit, 8-channel multiplexed successive approximation analog-to-digital converter modules. The P89LPC983 has a 10-bit, 4-channel multiplexed successive approximation analog-to-digital converter modules. A block diagram of the ADC is shown in Figure 20 "ADC block diagram".

8.4.4 Auto scan, continuous conversion mode

Any combination of the eight input channels can be selected for conversion. A conversion of each selected input will be performed and the result placed in the result register pair which corresponds to the selected input channel. The user may select whether an interrupt, if enabled, will be generated after either the first four conversions have occurred or all selected channels have been converted. If the user selects to generate an interrupt after the four input channels have been converted, a second interrupt will be generated after the remaining input channels have been converted. After all selected channels have been converted, the process will repeat starting with the first selected channel. Additional conversion results will again cycle through the eight result register pairs, overwriting the previous results. Continuous conversions continue until terminated by the user.

8.4.5 Dual channel, continuous conversion mode

This is a variation of the auto scan continuous conversion mode where conversion occurs on two user-selectable inputs. The result of the conversion of the first channel is placed in the result register pair, AD0DAT0R and AD0DAT0L. The result of the conversion of the second channel is placed in result register pair, AD0DAT1R and AD0DAT1L. The first channel is again converted and its result stored in AD0DAT2R and AD0DAT2L. The second channel is again converted and its result placed in AD0DAT3R and AD0DAT3L. An interrupt is generated, if enabled, after every set of four or eight conversions (user selectable).

8.4.6 Single step mode

This special mode allows ‘single-stepping’ in an auto scan conversion mode. Any combination of the eight input channels can be selected for conversion. After each channel is converted, an interrupt is generated, if enabled, and the A/D waits for the next start condition. May be used with any of the start modes.

8.5 Conversion start modes

8.5.1 Timer triggered start

An A/D conversion is started by the overflow of Timer 0. Once a conversion has started, additional Timer 0 triggers are ignored until the conversion has completed. The Timer triggered start mode is available in all ADC operating modes.

8.5.2 Start immediately

Programming this mode immediately starts a conversion. This start mode is available in all ADC operating modes.

8.5.3 Edge triggered

An A/D conversion is started by rising or falling edge of P1.4. Once a conversion has started, additional edge triggers are ignored until the conversion has completed. The edge triggered start mode is available in all ADC operating modes.

Table 13. Static characteristics *…continued*

V_{DD} = 2.4 V to 5.5 V unless otherwise specified.
T_{amb} = 40 °C to +85 °C for industrial applications, unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[1]	Max	Unit
$I_{DD(tpd)}$	total Power-down mode supply current	V_{DD} = 2.4 V	[3]	-	1	5	µA
		V_{DD} = 3.3 V	[3]	-	1	5	µA
		V_{DD} = 5.5 V	[3]	-	1	5	µA
$(dV/dt)_r$	rise rate	of V_{DD}; to ensure power-on reset signal		5	-	5000	V/S
V_{POR}	power-on reset voltage			-	-	0.5	V
V_{DDR}	data retention supply voltage			1.5	-	-	V
$V_{th(HL)}$	HIGH-LOW threshold voltage	except SCL, SDA		$0.22V_{DD}$	$0.4V_{DD}$	-	V
V_{IL}	LOW-level input voltage	SCL, SDA only		0.5	-	$0.4V_{DD}$	V
$V_{th(LH)}$	LOW-HIGH threshold voltage	except SCL, SDA		-	$0.6V_{DD}$	$0.7V_{DD}$	V
V_{IH}	HIGH-level input voltage	SCL, SDA only		$0.55V_{DD}$	-	5.5	V
V_{hys}	hysteresis voltage	port 1		-	$0.2V_{DD}$	-	V
V_{OL}	LOW-level output voltage	I_{OL} = 20 mA; V_{DD} = 2.4 V to 5.5 V all ports, all modes except high-Z	[4]	-	0.6	1.0	V
		I_{OL} = 3.2 mA; V_{DD} = 2.4 V to 5.5 V all ports, all modes except high-Z	[4]	-	0.2	0.3	V
V_{OH}	HIGH-level output voltage	I_{OH} = 20 µA; V_{DD} = 2.4 V to 5.5 V; all ports, quasi-bidirectional mode		V_{DD} 0.3	V_{DD} 0.2	-	V
		I_{OH} = 3.2 mA; V_{DD} = 2.4 V to 5.5 V; all ports, push-pull mode		V_{DD} 0.7	V_{DD} 0.4	-	V
		I_{OH} = 10 mA; V_{DD} = 2.4 V to 5.5 V; all ports, push-pull mode		-	V_{DD} 0.5	-	V
V_{xtal}	crystal voltage	on XTAL1, XTAL2 pins when XTAL1/XTAL2 is used as crystal input/output; with respect to V_{SS}		0.5	-	+4.0	V
		on XTAL1, XTAL2 pins when XTAL1/XTAL2 is used as GPIO; with respect to V_{SS}		0.5	-	+5.5	V
V_n	voltage on any other pin	with respect to V_{SS}	[5]	0.5	-	+5.5	V
C_{iss}	input capacitance		[6]	-	-	15	pF
I_{IL}	LOW-level input current	V_I = 0.4 V	[7]	-	-	80	µA
I_{LI}	input leakage current	$V_I = V_{IL}$, V_{IH}, or $V_{th(HL)}$	[8]	-	-	r1	µA
I_{THL}	HIGH-LOW transition current	all ports; V_I = 1.5 V at V_{DD} = 5.5 V	[9]	30	-	450	µA
$R_{RST\_N(int)}$	internal pull-up resistance on pin $\overline{RST}$	pin $\overline{RST}$		30	-	120	k :
BOD interrupt							

Table 15. Dynamic characteristics (18 MHz) *…continued*

V_{DD} = 3.6 V to 5.5 V unless otherwise specified.

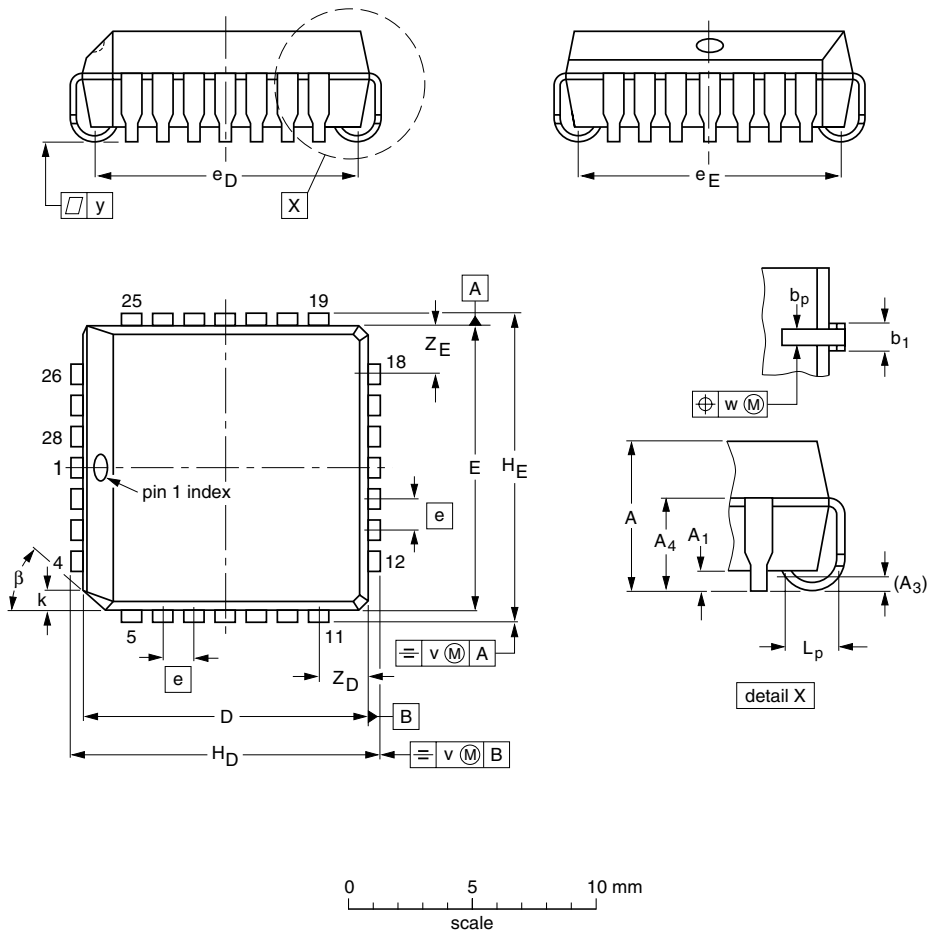
T_{amb} = 40 °C to +85 °C for industrial applications, unless otherwise specified.[1][2]

Symbol	Parameter	Conditions	Variable clock		f_{osc} = 18 MHz		Unit
			Min	Max	Min	Max	
$t_{SPILEAD}$	SPI enable lead time	see Figure 26, 27					
	slave		250	-	250	-	ns
t_{SPILAG}	SPI enable lag time	see Figure 26, 27					
	slave		250	-	250	-	ns
$t_{SPICLKH}$	SPICLK HIGH time	see Figure 24, 25, 26, 27					
	slave		$^{3}/_{CCLK}$	-	167	-	ns
	master		$^{2}/_{CCLK}$	-	111	-	ns
$t_{SPICLKL}$	SPICLK LOW time	see Figure 24, 25, 26, 27					
	slave		$^{3}/_{CCLK}$	-	167	-	ns
	master		$^{2}/_{CCLK}$	-	111	-	ns
t_{SPIDSU}	SPI data set-up time	see Figure 24, 25, 26, 27					
	master or slave		100	-	100	-	ns
t_{SPIDH}	SPI data hold time	see Figure 24, 25, 26, 27					
	master or slave		100	-	100	-	ns
t_{SPIA}	SPI access time	see Figure 26, 27					
	slave		0	80	0	80	ns
t_{SPIDIS}	SPI disable time	see Figure 26, 27					
	slave		0	160	-	160	ns
t_{SPIDV}	SPI enable to output data valid time	see Figure 24, 25, 26, 27					
	slave		-	160	-	160	ns
	master		-	111	-	111	ns
t_{SPIOH}	SPI output data hold time	see Figure 24, 25, 26, 27	0	-	0	-	ns
t_{SPIR}	SPI rise time	see Figure 24, 25, 26, 27					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns
t_{SPIF}	SPI fall time	see Figure 24, 25, 26, 27					
	SPI outputs (SPICLK, MOSI, MISO)		-	100	-	100	ns
	SPI inputs (SPICLK, MOSI, MISO, $\overline{SS}$)		-	2000	-	2000	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Parts are tested to 2 MHz, but are guaranteed to operate down to 0 Hz.

PLCC28: plastic leaded chip carrier; 28 leads **SOT261-2**



DIMENSIONS (mm dimensions are derived from the original inch dimensions)

UNIT	A	A_1 min.	A_3	A_4 max.	b_p	b_1	$D^{(1)}$	$E^{(1)}$	e	e_D	e_E	H_D	H_E	k	L_p	v	w	y	$Z_D^{(1)}$ max.	$Z_E^{(1)}$ max.	β
mm	4.57 4.19	0.51	0.25	3.05	0.53 0.33	0.81 0.66	11.58 11.43	11.58 11.43	1.27	10.92 9.91	10.92 9.91	12.57 12.32	12.57 12.32	1.22 1.07	1.44 1.02	0.18	0.18	0.1	2.16	2.16	45°
inches	0.180 0.165	0.02	0.01	0.12	0.021 0.013	0.032 0.026	0.456 0.450	0.456 0.450	0.05	0.43 0.39	0.43 0.39	0.495 0.485	0.495 0.485	0.048 0.042	0.057 0.040	0.007	0.007	0.004	0.085	0.085	

Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT261-2	112E08	MS-018	EDR-7319			~~99-12-27~~ 01-11-15

Fig 30. Package outline SOT261-2 (PLCC28)

16. Legal information

16.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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